

MULTICHIP MODULES

Systems Advantages, Major Constructions,
and Materials Technologies

EDITED BY

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A volume in the IEEE PRESS Selected Reprint Series,
prepared under the sponsorship of the IEEE Components, Hybrids,
and Manufacturing Technology Society.



The Institute of Electrical and Electronics Engineers, Inc., New York

Contents

PREFACE		ix
PART 1	INTRODUCTION	1
PART 2	ANALYSIS OF PACKAGING ISSUES	5
	New Packaging Strategy to Reduce System Costs	7
	J. W. Balde, <i>IEEE Transactions on Components, Hybrids, and Manufacturing Technology</i> (September, 1984)	
	Interconnection Costs of Various Substrates—The Myth of Cheap Wire	11
	W. H. Knausenberger and L. W. Schaper, <i>IEEE Transactions on Components, Hybrids, and Manufacturing Technology</i> (September, 1984)	
	Future of Multichip Modules in Electronics	14
	M. G. Sage, <i>Proceedings of NEPCON West</i> (1989)	
	Cost-Density Analysis of Interconnections	21
	G. Messner, <i>IEEE Transactions on Components, Hybrids, and Manufacturing Technology</i> (June, 1987)	
	Comparison of Wafer Scale Integration with VLSI Packaging Approaches	30
	C. A. Neugebauer and R. O. Carlson, <i>IEEE Transactions on Components, Hybrids, and Manufacturing Technology</i> (June, 1987)	
	Technology and Design for High Speed Digital Components in Advanced Applications	36
	R. P. Vidano, J. P. Cummings, R. J. Jensen, W. L. Walters, and M. J. Helix, <i>Proceedings of the 33rd Electronic Components Conference</i> (1983)	
	Multichip Module Designs for High Performance Applications	46
	C. Neugebauer, R. O. Carlson, R. A. Fillion, and T. R. Haller, <i>Proceedings of NEPCON West</i> (1989)	
	Multichip Packaging and the Need for New Materials	53
	J. W. Balde, <i>Journal of Electronic Materials</i> (February, 1989)	
	Analysis of Materials and Structure Tradeoffs in Thin and Thick Film Multi-Chip Packages	60
	J. P. Krusius and W. E. Pence, <i>Proceedings of the 39th Electronic Components Conference</i> (1989)	
	A Comparison of Thin Film, Thick Film, and Co-fired High Density Ceramic Multilayer with the Combined Technology: T&T HDCM (Thin Film and Thick Film High Density Ceramic Module)	66
	M. Terasawa, S. Minami, and J. Rubin, <i>The International Journal for Hybrid Microelectronics</i> , (vol. 6, no. 1, 1983)	
PART 3	COFIRED CERAMIC TECHNOLOGY	75
	Multilayer Ceramics	77
	B. Schwartz, <i>Materials Research Society Symposia Proceedings</i> (1985)	
	Microelectronic Packaging	82
	A. J. Blodgett, Jr., <i>Scientific American</i> (July, 1983)	
	A Multilayer Ceramic Multichip Module	93
	A. J. Blodgett, Jr., <i>IEEE Transactions on Components, Hybrids, and Manufacturing Technology</i> (December, 1980)	
	VLSI Packaging Technique Using Liquid-Cooled Channels	97
	T. Kishimoto and T. Ohsaki, <i>IEEE Transactions on Components, Hybrids, and Manufacturing Technology</i> (December, 1986)	

PART 4	THIN FILM MULTILAYER MODULES ON SILICON	105
	Advanced Packaging Concepts—Microelectronics Multiple Chip Modules Utilizing Silicon Substrates	107
	A. A. Evans and J. K. Hagge, <i>Proceedings of the 1st International SAMPE Electronics Conference</i> (1987)	
	Multichip Packaging Design for VLSI-Based Systems	116
	C. J. Bartlett, J. M. Segelken, and N. A. Teneketges, <i>IEEE Transactions on Components, Hybrids, and Manufacturing Technology</i> (December, 1987)	
	High-Density Multichip Interconnect (HDMI)	123
	K. P. Shambrook and P. A. Trask, <i>Proceedings of the 39th Electronic Components Conference</i> (1989)	
	Multichip Assembly with Flipped Integrated Circuits	130
	K. G. Heinen, W. H. Schroen, D. R. Edwards, A. M. Wilson, R. J. Stierman, and M. A. Lamson, <i>Proceedings of the 39th Electronic Components Conference</i> (1989)	
	A Series of Demonstrators to Assess Technologies for Silicon Hybrid Multichip Modules	139
	L. C. Early, <i>Proceedings of the 39th Electronic Components Conference</i> (1989)	
	High-Density Multilayer Interconnection with Photo-Sensitive Polyimide Dielectric and Electroplating Conductor	144
	K. Moriya, T. Ohsaki, and K. Katsura, <i>Proceedings of the 34th Electronic Components Conference</i> (1984)	
	High-Density Multichip Module by Chip-on-Wafer Technology	150
	S. Kimijima, T. Miyagi, T. Sudo, and O. Shimada, <i>Proceedings of the International Symposium on Microelectronics</i> (1988)	
	An Electrically Programmable Silicon Circuit Board	156
	A. A. Bogdan, <i>Proceedings of BUSCON '87</i> (1987)	
	Multichip Packaging Technology with Laser-Patterned Interconnects	162
	A. T. Barfknecht, D. B. Tuckerman, J. L. Kaschmitter, and B. M. McWilliams, <i>Proceedings of the 39th Electronic Components Conference</i> (1989)	
	Multi-Chip Modules Without Thin Film Wafer Processing	167
	D. Pommer and J. Chiechi, <i>Proceedings of the 9th International Electronic Packaging Conference</i> (1989)	
	Packaging Design of a SiC Ceramic Multi-Chip RAM Module	184
	K. Okutani, K. Otsuka, K. Sahara, and K. Satoh, <i>Proceedings of the 1984 International Electronic Packaging Conference</i> (1984)	
	Ultra-Reliable Packaging for Silicon-on-Silicon WSI	190
	J. K. Hagge, <i>Proceedings of the 38th Electronic Components Conference</i> (1988)	
	Ultra-Reliable HWSI with Aluminum Nitride Packaging	201
	J. K. Hagge, <i>Proceedings of NEPCON West</i> (1989)	
	Passive-Silicon-Carrier Design and Characteristics	211
	H. Schettler, <i>Proceedings of the 40th Electronic Components & Technology Conference</i> , Vol. 1 (1990)	
PART 5	THIN FILM MULTILAYER MODULES ON CERAMIC OR METAL	215
	The Thin-Film Module as a High-Performance Semiconductor Package	217
	C. W. Ho, D. A. Chance, C. H. Bajorek, and R. E. Acosta, <i>IBM Journal of Research and Development</i> (May, 1982)	
	Copper/Polyimide Materials System for High Performance Packaging	228
	R. J. Jensen, J. P. Cummings, and H. Vora, <i>IEEE Transactions on Components, Hybrids, and Manufacturing Technology</i> (December, 1984)	
	Packaging Technology for the NEC SX Supercomputer	238
	T. Watari and H. Murano, <i>IEEE Transactions on Components, Hybrids, and Manufacturing Technology</i> (December, 1985)	
	A New Multi-Chip Module Using a Copper Polyimide Multi-Layer Substrate	244
	S. Sasaki, T. Kon, and T. Ohsaki, <i>Proceedings of the 39th Electronic Components Conference</i> (1989)	

Contents

High-Performance VLSI Through Package-Level Interconnects	251
L. Liang, J. D. Wilson, N. Brathwaite, L. E. Mosley, and D. Love, <i>Proceedings of the 39th Electronic Components Conference</i> (1989)	
High Density Multilevel Copper-Polyimide Interconnects	257
S. Poon, J. T. Pan, T.-C. Wang, and B. Nelson, <i>Proceedings of NEPCON West</i> (1989)	
High Density Hybrid IC Module by MCPH Technology	275
M. Takada, T. Makita, E. Gofuku, K. Miyake, A. Endo, K. Adachi, Y. Morihira, and H. Takasago, <i>Proceedings of the International Symposium on Microelectronics</i> (1988)	
Multichip Packaging for Supercomputers	280
I. Turlik, A. Reisman, R. Darveaux, and L.-T. Hwang, <i>Proceedings of NEPCON West</i> (1989)	
Process Considerations in Fabricating Thin Film Multichip Modules	290
T. G. Tessier, I. Turlik, G. M. Adema, D. Sivan, E. K. Yung, and M. J. Berry, <i>Proceedings of the 1989 International Electronic Packaging Symposium</i> (1989)	
A Fine-Line Multilayer Substrate with Photo-Sensitive Polyimide Dielectric and Electroless Copper Plated Conductors	311
T. Ohsaki, T. Yasuda, S. Yamaguchi, and T. Kon, <i>Proceedings of the IEEE International Electronic Manufacturing Technology Symposium</i> (1987)	
High-Density Interconnects Using Laser Lithography	317
L. M. Levinson, C. W. Eichelberger, R. J. Wojnarowski, and R. O. Carlson, <i>Proceedings of the International Symposium on Microelectronics</i> (1988)	
High Density/High Speed Multi-Chip Packaging	323
S. Lebow, <i>Proceedings of the 1986 International Electronic Packaging Conference</i> (1986)	
Fluoropolymer Composite Multichip Modules	330
R. T. Traskos and S. C. Lockard, <i>Proceedings of the 9th International Electronic Packaging Conference</i> , Vol. 1 (1989)	
A New Multichip Interconnect Technology	339
S. L. Jacobs and W. E. Guthrie, <i>Proceedings of the 1989 International Electronic Packaging Symposium</i> (1989)	
A Copper/Polyimide Metal-Base Packaging Technology	355
H. Takasago, K. Adachi, and M. Takada, <i>Journal of Electronic Materials</i> (February, 1989)	
Very High Speed Multilayer Interconnect Using Photosensitive Polyimides	363
R. L. Hubbard and G. Lehman-Lamer, <i>Proceedings of the International Symposium on Microelectronics</i> (1988)	
Lift-Off Techniques for Multichip Modules	366
A. Schiltz, M. J. Bouzid, D. Jourdain, J. Torres, J. Palleau, J. C. Oberlin, D. Laviale, and J. Nechtschein, <i>Proceedings of NEPCON West</i> (1990)	
Multi Chip Modules for Telecom Applications	375
K. Gustafsson and G. Flodman, <i>Proceedings of the 8th International Electronic Manufacturing Technology Symposium</i> (1990)	
PART 6 THIN FILM DIELECTRIC MATERIALS	385
Polymer Dielectric Options for Thin Film Packaging Applications	387
T. G. Tessier, G. M. Adema, and I. Turlik, <i>Proceedings of the 39th Electronic Components Conference</i> (1989)	
Evaluation of Polyimides as Dielectric Materials for Multichip Packages with Multilevel Interconnection Structure	395
A. W. Lin, <i>Proceedings of the 39th Electronic Components Conference</i> (1989)	
Benzocyclobutene (BCB) Dielectrics for the Fabrication of High Density Thin Film Multichip Modules	402
D. Burdeaux, P. Townsend, J. Carr, and P. Garrou, <i>Journal of Electronic Materials</i> (December, 1990)	
New Low Coefficient of Thermal Expansion Polyimide for Inorganic Substrates	412
B. T. Merriman, J. D. Craig, A. E. Nader, D. L. Goff, M. T. Pottiger, and W. J. Lautenberger, <i>Proceedings of the 39th Electronic Components Conference</i> (1989)	
The Application of Photosensitive Polyimide Dielectrics in Thin-Film Multilayer Hybrid Circuit Structures	417
G. V. Clatterbaugh and H. K. Charles, Jr., <i>Proceedings of the International Symposium on Microelectronics</i> (1988)	

PART 7	COFIRED GLASS/CERAMIC TECHNOLOGY	433
	Low Temperature Co-Fireable Ceramics: A New Approach for Electronic Packaging	435
	A. L. Eustice, S. J. Horowitz, J. J. Stewart, A. R. Travis, and H. T. Sawhill, <i>Proceedings of the 36th Electronic Components Conference</i> (1986)	
	A New Low Temperature Fireable Ag Multilayer Ceramic Substrate Having Post-Fired Cu Conductor (LFC-2)	446
	S. Nishigaki, J. Fukuta, S. Yano, H. Kawabe, K. Noda, and M. Fukaya, <i>Proceedings of the International Symposium on Microelectronics</i> (1986)	
	New TCE-Matched Glass-Ceramic Multi-Chip Module: I. Electrical Design and Characterization	455
	W. E. Pence, J. P. Krusius, R. Subrahmanyam, C. Y. Li, G. Carrier, G. L. Francis, R. J. Paisley, and L. M. Holleran, <i>Proceedings of the 39th Electronic Components Conference</i> (1989)	
	New TCE-Matched Glass-Ceramic Multi-Chip Module: II. Materials, Mechanical, and Thermal Aspects	460
	G. Carrier, G. L. Francis, R. J. Paisley, R. Subrahmanyam, C. Y. Li, W. E. Pence, J. P. Krusius, and L. M. Holleran, <i>Proceedings of the 39th Electronic Components Conference</i> (1989)	
	Low Dielectric Constant Multilayer Glass-Ceramic Substrate with Ag-Pd Wiring for VLSI Package	464
	Y. Shimada, Y. Yamashita, and H. Takamizawa, <i>IEEE Transactions on Components, Hybrids, and Manufacturing Technology</i> (March, 1988)	
	Low Temperature Co-Fireable Ceramics with Co-Fired Resistors	472
	H. T. Sawhill, A. L. Eustice, S. J. Horowitz, J. Gar-El, and A. R. Travis, <i>Proceedings of the International Symposium on Microelectronics</i> (1986)	
PART 8	THERMAL ANALYSIS OF MULTICHIP MODULES	481
	Thermal Management of Air- and Liquid-Cooled Multichip Modules	483
	A. Bar-Cohen, <i>IEEE Transactions on Components, Hybrids, and Manufacturing Technology</i> (June, 1987)	
	Internal Thermal Resistance of a Multi-Chip Packaging Design for VLSI-Based Systems	500
	Y. C. Lee, H. T. Ghaffari, and J. M. Segelken, <i>Proceedings of the 38th Electronic Components Conference</i> (1988)	
	Thermal/Stress Analysis of a Multichip Package Design	509
	R. Darveaux, L.-T. Hwang, A. Reisman, and I. Turlik, <i>Proceedings of the 39th Electronic Components Conference</i> (1989)	
	Thermal Management Considerations for a Low-Temperature, Co-Fireable Ceramic System	513
	E. L. Rich III, S. K. Suko, A. J. Martin, B. H. Smith, D. G. Onn, A. J. Whittaker, R. E. Giedd, and F. K. Patterson, <i>Proceedings of the International Symposium on Microelectronics</i> (1987)	
PART 9	ELECTRICAL ANALYSIS AND TESTING OF MULTICHIP MODULES	525
	Electrical Characteristics of Copper/Polyimide Thin-Film Multilayer Interconnects	527
	T. A. Lane, F. J. Belcourt, and R. J. Jensen, <i>IEEE Transactions on Components, Hybrids, and Manufacturing Technology</i> (December, 1987)	
	Performance Characteristics of Thin Film Multilayer Interconnects in the 1-10 GHz Frequency Range	536
	D. J. Schwab, R. L. Thompson, B. K. Gilbert, K. Jayaraj, T. J. Moravec, R. J. Jensen, and R. Sainati, <i>Proceedings of the 39th Electronic Components Conference</i> (1989)	

Contents

Transmission Lines for Wafer Scale Integration	543
H. Stopper, <i>Proceedings of the 1st International Conference on Computer Technology, Systems, and Applications</i> (1987)	
Waveguides as Interconnects for High Performance Packaging	547
S. E. Schacham, T. G. Tessier, H. Merkelo, L.-T. Hwang, and I. Turlik, <i>Proceedings of the 9th International Electronics Packaging Conference</i> , Vol. II (1989)	
A Comparative Study of Interconnect Technologies	557
V. K. Nagesh, D. Miller, and L. Moresco, <i>Proceedings of the 9th International Electronics Packaging Conference</i> , Vol. I (1989)	
Design and Testing of High Density Interconnection Substrates	567
C. Hilbert and C. Rathmell, <i>Proceedings of NEPCON West</i> (1990)	
Application of Automatic Optical Inspection (AOI) in the Manufacturing Technology of Thin Film Multichip Module (MCM)	580
G. Dishon and O. Hecht, <i>Proceedings of NEPCON West</i> (1990)	
EPILOGUE	593
AUTHOR INDEX	595
SUBJECT INDEX	597
EDITORS' BIOGRAPHIES	603